



P A T E N T

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cabuz et al.

Serial No.: 09/749,171

Examiner: Simkovic, Viktor

Filed: December 27, 2000

Group Art Unit: 2812

For: THIN SILICON MICROMACHINED STRUCTURES

Docket No.: 1100.1116101 (H16-26635)

AFTER FINAL AMENDMENT

**Box Amendment**

Assistant Commissioner for Patents  
Washington, D.C. 20231

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And  
N/E  
J. M. C. M. L.  
10/2/02  
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**CERTIFICATE UNDER 37 C.F.R. 1.10:** The undersigned hereby certifies that this paper or papers, as described herein, are being deposited in the United States Postal Service, "Express Mail Post Office to Addressee" having an Express Mail mailing label number of: EL921287618US, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C., 20231 on 24th day of September, 2002.

By

*Lynn Thompson*  
Lynn Thompson

Dear Sir:

In response to the Final Office Action dated May 24, 2002, please amend the above-captioned patent application as follows:

In the Claims

Please cancel claim 22.

Please add newly presented claim 24.

24. (Newly Presented) A method for making a thin structure, comprising:

providing a first wafer or substrate;